



Material Content Data Sheet



Sales Product Name		TLE4678EL		Issued		27. September 2017		
MA#		MA000970080						
Package		PG-SSOP-14-2		Weight*		83.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.312	3.96	3.96	39621	39621
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		412	
	non noble metal	iron	7439-89-6	0.689	0.82		8242	
wire	non noble metal	copper	7440-50-8	27.978	33.47	34.34	334669	343426
	noble metal	gold	7440-57-5	0.195	0.23	0.23	2337	2337
encapsulation	organic material	carbon black	1333-86-4	0.096	0.11		1149	
	plastics	epoxy resin	-	4.420	5.29		52874	
	inorganic material	silicondioxide	60676-86-0	43.530	52.07	57.47	520699	574722
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11676	11676
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9182	9182
glue	plastics	epoxy resin	-	0.398	0.48		4759	
	noble metal	silver	7440-22-4	1.194	1.43	1.91	14277	19036
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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